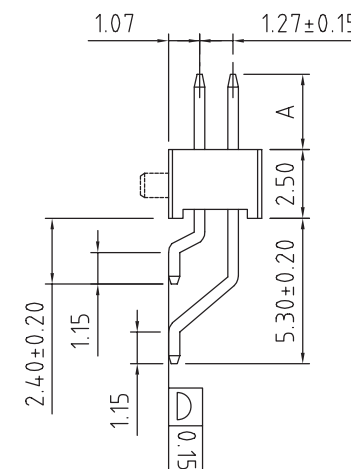
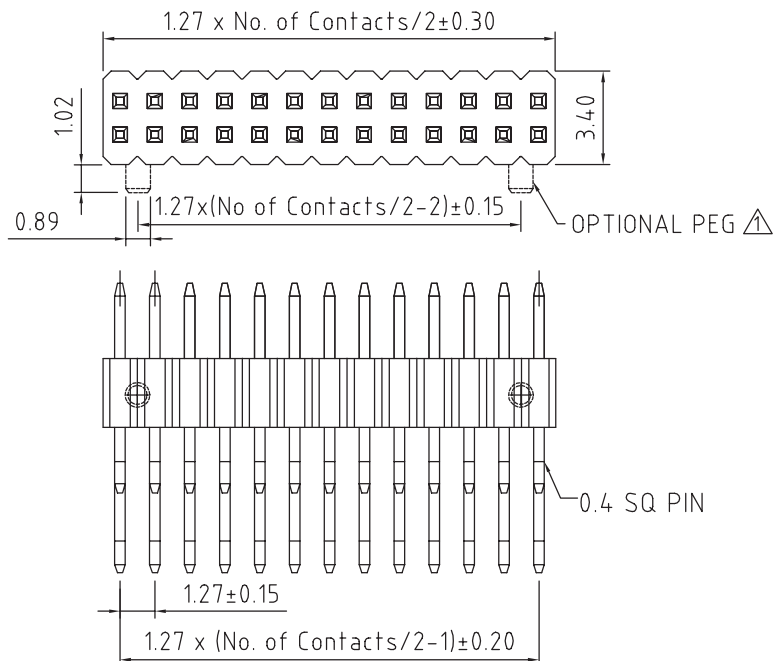


BB02-NE-A :- 1.27mm X 1.27mm ( 0.05" X 0.05" ) SMD PIN HEADER, DUAL ROW, R/A - 04 TO 80 CONTACTS

## SPECIFICATIONS

CURRENT RATING	1 AMP
INSULATOR RESISTANCE	1000 MEGOHMS MIN.
CONTACTS RESISTANCE	20 m OHMS MAX.
DIELECTRIC WITHSTANDING	300V AC
OPERATING TEMPERATURE	-40°C TO +105°C
CONTACT MATERIAL	BRASS
INSULATOR MATERIAL	POLYESTER UL 94V-0 STANDARD: LCP
PLATING	GOLD, TIN, OR SELECTIVE OVER 30-50U" NICKEL
SOLDERABILITY	IR REFLOW: 260°C FOR 10 SEC MANNUAL SOLDER: 350°C FOR 3-5 SEC

MATES WITH :-	BB02-CL	BB02-CU
	BB02-CM	BB02-CW
	BB02-CN	BB02-CZ
	BB02-CQ	
	BB02-CR	



## HOW TO ORDER

B B 0 2 - N E X X 1 - X A X - X X X 0 0 0

NO. OF CONTACTS  
06 TO 66 (W/PEG)  
04 TO 80 (W/O PEG)

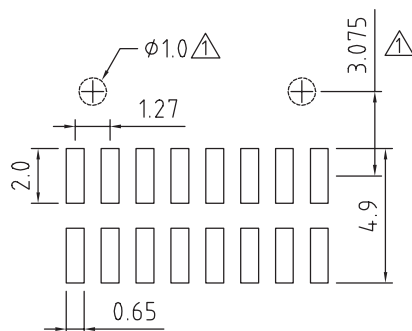
CONTACT PLATING OPTIONS  
K = GOLD FLASH (STANDARD)  
A = 10U" GOLD ON CONTACT/GOLD FLASH ON TAIL  
B = 15U" GOLD ON CONTACT/GOLD FLASH ON TAIL  
C = 30U" GOLD ON CONTACT/GOLD FLASH ON TAIL  
T = BRIGHT TIN  
M = MATT TIN  
D = GOLD FLASH ON CONTACT/BRIGHT TIN ON TAIL  
E = 10U" GOLD ON CONTACT/BRIGHT TIN ON TAIL  
F = 15U" GOLD ON CONTACT/BRIGHT TIN ON TAIL  
G = 30U" GOLD ON CONTACT/BRIGHT TIN ON TAIL

INSULATOR  
HEIGHT 3.4MM


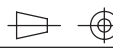
PACKAGING OPTIONS  
3 - TUBE  
4 - TUBE + FILM  
6 - T & R  
7 - T & R + FILM

LOCATING PEGS OPTION  
A = WITH PEG  
0 = WITHOUT PEG

PIN LENGTH 'A' (1/10mm)  
PLEASE SPECIFY PIN  
LENGTH REQUIRED IN mm  
I.E. 2.5mm = 25  
STANDARD = 38  
TOL. ±0.25mm



RECOMMENDED PC BOARD SMD LAYOUT  
(TOLERANCE: ±0.05)

REV. DATE & DRN	Scale: 5:1	THIRD ANGLE	Unstated Tolerances:	Material		Type: BB02-NE
11 21/03/07 - NYW RELEASE	Drawn: NYW		X. ± 0.30	SEE NOTE		BB02-NE-A
12 21/03/07 - NYW ADD LOCATING PEG OPTION.	App'd: XXX		X. ± 0.25			Drawing Number:
13 21/03/07 - NYW ADD PACK OPTION 4.	Date: 5 JAN '09	Title PIN HEADER	.XX ± 0.15	NOT TO SCALE		Sheet 1 of 1
14 05/01/09 - NYW PLATING MODIFICATION. CHANGE INSULATOR TO LCP. DRAWING MODIFICATION.		Revision: 14	.XXX ± 0.10	UNIT: mm		Drawing © E and O E